



# EDCON-COMPONENTS



Designed for surface mounting on high density circuit board

Emboss carrier tape packing systems is available for automatic insertion



## Technical Informations

Voltage:	<b>25Volt</b>
Range:	<b>22µF</b>
Dimension; D x L mm	<b>6,3x5,4mm</b>
Impedance (Ω) max., at20°C, 100hKz	<b>13,7Ω</b>
Ripple Current (mA rms) at 105°C, 100kHz	<b>52mA</b>

Ordering Code			
<b>250</b>	<b>Voltage</b>		
<b>220</b>	<b>Range</b>		
<b>D=</b>	<b>C</b>	<b>L=</b>	<b>0</b>

- Low Leakage current ( 0,5µA to 3,3µA max).
- Low cost for replacement of some tantalum applications
- Low Impedance with Operating Temperatur Range of -40°C ~ +85°C
- Load Life of 2000hours

<b>Leakage current max.</b>	I = 0,002CV or 0,5µA whichever is greater ( after 2 minutes)	
-----------------------------	--	--

<b>Capacitance tolerance</b>	± 20% at 120Hz, 20°C											
<b>Dissipation factor max. (at 120Hz, 20°C)</b>		WV										
	Tanδ	Ø4 ~ Ø6,3mm	6,3	10	16	25	35	50				
			0,24	0,20	0,16	0,14	0,12	0,10				

<b>Low Temperatur characteristics ( Impedance ratio at 120Hz )</b>		WV										
		Z-25°C / Z+20°C	6,3	10	16	25	35	50				
		Z-40°C / Z+20°C	4	3	2	2	2	2				
			8	6	4	4	3	3				

<b>Load Life ( after application of the rated voltage for 2000hrs at 85°C</b>	Leakage current	Less than specified value
	Capacitance Change	Within ±25% of initial value
	Tanδ	Less than 200% of specified value
	Ø4 ~ Ø6,3x5,4: 1000hours	

<b>CHIP Low Leakage Current</b>	
Part No.:	<b>I15004</b>

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.06.2014	Customer:
APPD:	Schumi			FINISH	Jamy		Sheet No.	2 from 7		

# EDCON-COMPONENTS



Designed for surface mounting on high density circuit board  
 Emboss carrier tape packing systems is available for automatic insertion



\_\_\_\_\_

<b>Resistance to soldering heat</b>	After reflow soldering and resistance at room temperature, they meet the characteristics requirements listed at underside	
	Leakage current	Less than specified value
	Capacitance Change	Within $\pm 10\%$ of initial value
	Tan $\delta$	Less than specified value

FREQUENCY COEFFICIENT OF PERMISSIBLE RIPPLE CURRENT					
Frequency	50Hz	120Hz	300Hz	1KHz	10KHz $\leq$
Coefficient	0,70	1,00	1,17	1,36	1,50

<b>CHIP Low Leakage Current</b>
Part No.: <b>I15004</b>
Customer:

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.06.2014
APPD:	Schumi			FINISH	Jamy		Sheet No.		3 from 7

# EDCON-COMPONENTS



Designed for surface mounting on high density circuit board

Emboss carrier tape packing systems is available for automatic insertion

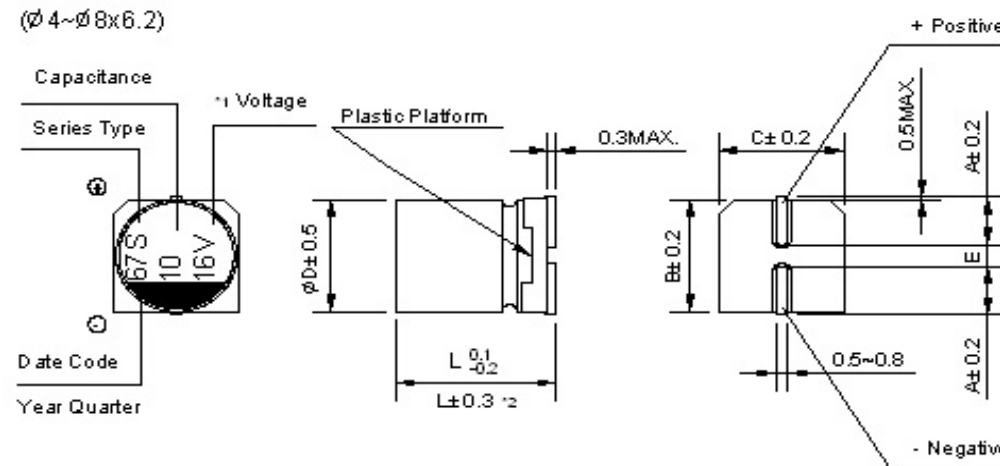


## Technical Drawing

### Dimension of Size Ø 8x10,5 ~ 16mm



### Dimension of Size Ø 4~ 8x6,2mm



D x L	Ø 4 x 5,4	Ø 5 x 5,4	Ø 6,3 x 5,4	Ø 6,3 x 7,7						
A	2,0	2,2	2,6	2,6						
B	4,3	5,3	6,6	6,6						
C	4,3	5,3	6,6	6,6						
E +/-0.2	1,0	1,3	1,9	1,9						
L	5,4	5,4	5,4	7,7						

\*1 Voltage mark (6V) represents 6,3V for Ø 4 ~ 10mm

\*3 (L +/- 0.5) is applicable to Ø 8x10,5 ~ Ø 10mm

\*2 (L +/- 0.3) is applicable to Ø 6,3 ~ 7.7 and Ø 8 + 6,2mm

\*4 (L +/- 1.0) is applicable to Ø 12,5 ~ Ø 16mm

RE. Date code and seriew type -1st digit for Year 2nd digit for Quarter, 4 quarter codes in one year area 1,4,7,0

3rd character for Serie S

**CHIP Low Leakage Current**

Part No.: **I15004**

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.06.2014	Customer:
APPD:	Schumi			FINISH	Jamy		Sheet No.	4 from 7		

[www.edcon-components.com](http://www.edcon-components.com)

email: [info@edcon-components.com](mailto:info@edcon-components.com)



# EDCON-COMPONENTS



Designed for surface mounting on high density circuit board

Emboss carrier tape packing systems is available for automatic insertion



## Ordering Informations

Serie	Voltage Code	Tolerance Code	Range Code	Size Code D	Size Code L	Special function	ROHS	Packing Code		
-------	--------------	----------------	------------	-------------	-------------	------------------	------	--------------	--	--

<b>I15004</b>	<b>250</b>	<b>M</b>	<b>220</b>	<b>C</b>	<b>0</b>	<b>XX</b>	<b>R</b>	<b>TR</b>		
---------------	------------	----------	------------	----------	----------	-----------	----------	-----------	--	--

look table Voltage Code	<b>M= ±20%</b>	Ordering Code Range	Look table Code D	Look table Code L	<b>XX= No function</b>	<b>R= ROHS Conform</b> <b>N= NON ROHS Conform</b>	<b>TR= Tape Reel Packing</b> <b>BU= Bulk-Ware</b>		
-------------------------	----------------	---------------------	-------------------	-------------------	------------------------	--	--	--	--

<b>CHIP Low Leakage Current</b>
Part No.: <b>I15004</b>
Customer:

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.06.2014
APPD:	Schumi			FINISH	Jamy		Sheet No.		6 from 7

# EDCON-COMPONENTS



Designed for surface mounting on high density circuit board  
 Emboss carrier tape packing systems is available for automatic insertion



## Soldering Profile Curve

### Classification Reflow Profile (JEDEC J-STD-020C)



**CHIP Low Leakage Current**

Part No.: **I15004**

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.06.2014
APPD:	Schumi			FINISH	Jamy		Sheet No.	7 from 7	

Customer: